

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	2.80mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 6 MIL
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 MIL

MINIMUM ANNULAR RING 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
 HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
 FR-408 FR-4 High Tg OTHER _____
 THICKNESS: 62 MIL (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2
 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FILES
 PTH COPPER THICKNESS: 20-30 um OTHER _____

BOARD FINISH:
 SILKSCREEN: TOP BOTTOM
 SILKSCREEN COLOR: WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN OTHER _____
 MATTE SEMI-GLOSS

SURFACE FINISH: IMMERSION GOLD (ENIG) ENIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

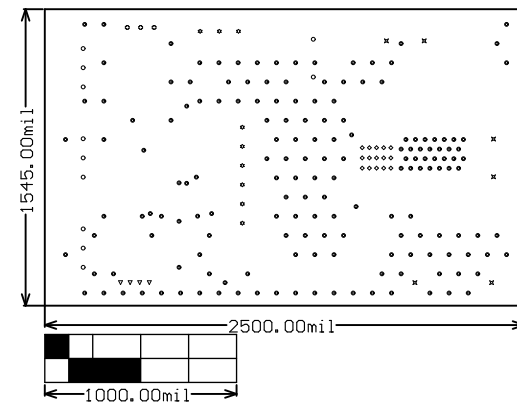
ARRAY/PANEL: CUT AND TRIM PER M1 BOARD OUTLINE
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI IPC-A-600F CLASS -> 1 2 3
 RoHS OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
 PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER
 ALL BOARDS MUST MEET THE UL MOT 130 C HEAT RATING

ADDITIONAL REQUIREMENTS:
 MICROSECTION: YES

BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
 XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
 OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
 LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE
 TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
◇	15	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
●	167	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	3	17.72mil (0.450mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
○	11	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	9	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	6	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
	215 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: MD014	REV: B	SUN REV: Not In VersionControl
LAYER NAME = 0005-0-14 0005-0-14	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 1/15/2020 1:58:53 PM	TEXAS INSTRUMENTS	

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LAYOUT BY:
Hector Hernandez
 ALTUM DESIGNER VERSION:
18.1.11.251